

**PROVISIONAL GRADE CARD**

Name : MHAISKE AKSHAY ANAND

Enrolment No. : MT23MTE001

Branch : MATERIALS ENGG.

Degree : Master of Technology

Course	Title	Cr	Gr	Course	Title	Cr	Gr
AUTUMN (July-Nov)2023							
MML501	INTRODUCTION TO METALS & ALLOYS (DC)	3	AA				
MML506	STRUCTURE AND CHARACTERIZATION OF MATERIALS (DC)	3	BC				
MML507	POLYMER ENGINEERING (DC)	3	CC				
MML509	CERAMIC ENGINEERING (DC)	3	BB				
MML511	CASTING & SOLIDIFICATION (DE)	3	BB				
MML525	THERMODYNAMICS OF MATERIALS (DC)	3	BB				
MMP501	INTRODUCTION TO METALS & ALLOYS (DC)	1	AB				
MMP506	STRUCTURE AND CHARACTERIZATION OF MATERIALS (DC)	1	BB				
MMP510	MATERIALS ENGINEERING LAB (DC)	1	AA				

SGPA	Credit		EGP		SGPA		CGPA	Credit		EGP		CGPA	
	21	168	8.00	CGPA	21	168		8.00					
DE 3	DC 18	HM 0	OC 0	0	DE 3	DC 18	HM 0	OC 0	0				
AU 0	ES 0	BS 0	Total	21	AU 0	ES 0	BS 0	Total	21				

Note : THIS GRADE CARD IS EXCLUSIVELY FOR INTERNAL USE

Medium of Instruction : English

Abbreviations : Cr - Credits, Gr - Grade, AU - Audit, EGP - Earned Grade Points

SGPA - Semester Grade Point Average, CGPA - Cumulative Grade Point Average, W - repeat the Course

This is a computer generated document and it does not require any signature(Condition Apply)

(This Statement is subject to correction, if any)

Date : 18-Jan-2024

Asst. Registrar (Examination)

**PROVISIONAL GRADE CARD**

Name : PRAMOD RAVINDRA KUSHWAHA

Enrolment No. : MT22MTE001

Branch : MATERIALS ENGG.

Degree : Master of Technology

Course	Title	Cr	Gr	Course	Title	Cr	Gr
AUTUMN (July-Nov)2022				SPRING (Jan - May) 2023			
MML501	INTRODUCTION TO METALS & ALLOYS (DC)	3	CD	MML502	DESIGN & SELECTION OF MATERIALS (DC)	3	CC
MML506	STRUCTURE AND CHARACTERIZATION OF MATERIALS (DC)	3	CD	MML512	DEFORMATION BEHAVIOUR OF MATERIALS (DE)	3	AB
MML507	POLYMER ENGINEERING (DC)	3	CC	MML518	CORROSION PROCESS & CONTROL (DE)	3	BC
MML509	CERAMIC ENGINEERING (DC)	3	BC	MML529	PHASE TRANSFORMATION (DC)	3	AB
MML511	CASTING & SOLIDIFICATION (DE)	3	BB	MML545	NON DESTRUCTIVE EVALUATION (DE)	3	BB
MML525	THERMODYNAMICS OF MATERIALS (DC)	3	BB	MML546	WELDING AND JOINING (DE)	3	BC
MMP501	INTRODUCTION TO METALS & ALLOYS (DC)	1	AB	MMP545	NON DESTRUCTIVE EVALUATION (DE)	1	AA
MMP506	STRUCTURE AND CHARACTERIZATION OF MATERIALS (DC)	1	BC				
MMP510	MATERIALS ENGINEERING LAB (DC)	1	AB				

SGPA	Credit	EGP	SGPA	CGPA	Credit	EGP	CGPA
	21	142	6.76		21	142	6.76
DE 3	DC 18	HM 0	OC 0	DE 3	DC 18	HM 0	OC 0
AU 0	ES 0	BS 0	Total 21	AU 0	ES 0	BS 0	Total 21

SGPA	Credit	EGP	SGPA	CGPA	Credit	EGP	CGPA
	19	148	7.79		40	290	7.25
DE 13	DC 6	HM 0	OC 0	DE 16	DC 24	HM 0	OC 0
AU 0	ES 0	BS 0	Total 19	AU 0	ES 0	BS 0	Total 40

AUTUMN (July-Nov)2023

MMD501 PROJECT PHASE - I (DC) 6 AA

SGPA	Credit	EGP	SGPA	CGPA	Credit	EGP	CGPA
	6	60	10.00		46	350	7.61
DE 0	DC 6	HM 0	OC 0	DE 16	DC 30	HM 0	OC 0
AU 0	ES 0	BS 0	Total 6	AU 0	ES 0	BS 0	Total 46

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